

SOT1622-4

BGA783, plastic, ball grid array; 783 balls; 1 mm pitch; 29 mm x 29 mm x 2.8 mm body

4 January 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA783
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	04-01-2016
Manufacturer package code	98ARS10526D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	29	-	mm
package width	-	29	-	mm
package height	-	2.8	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	783	-	



2 Package outline

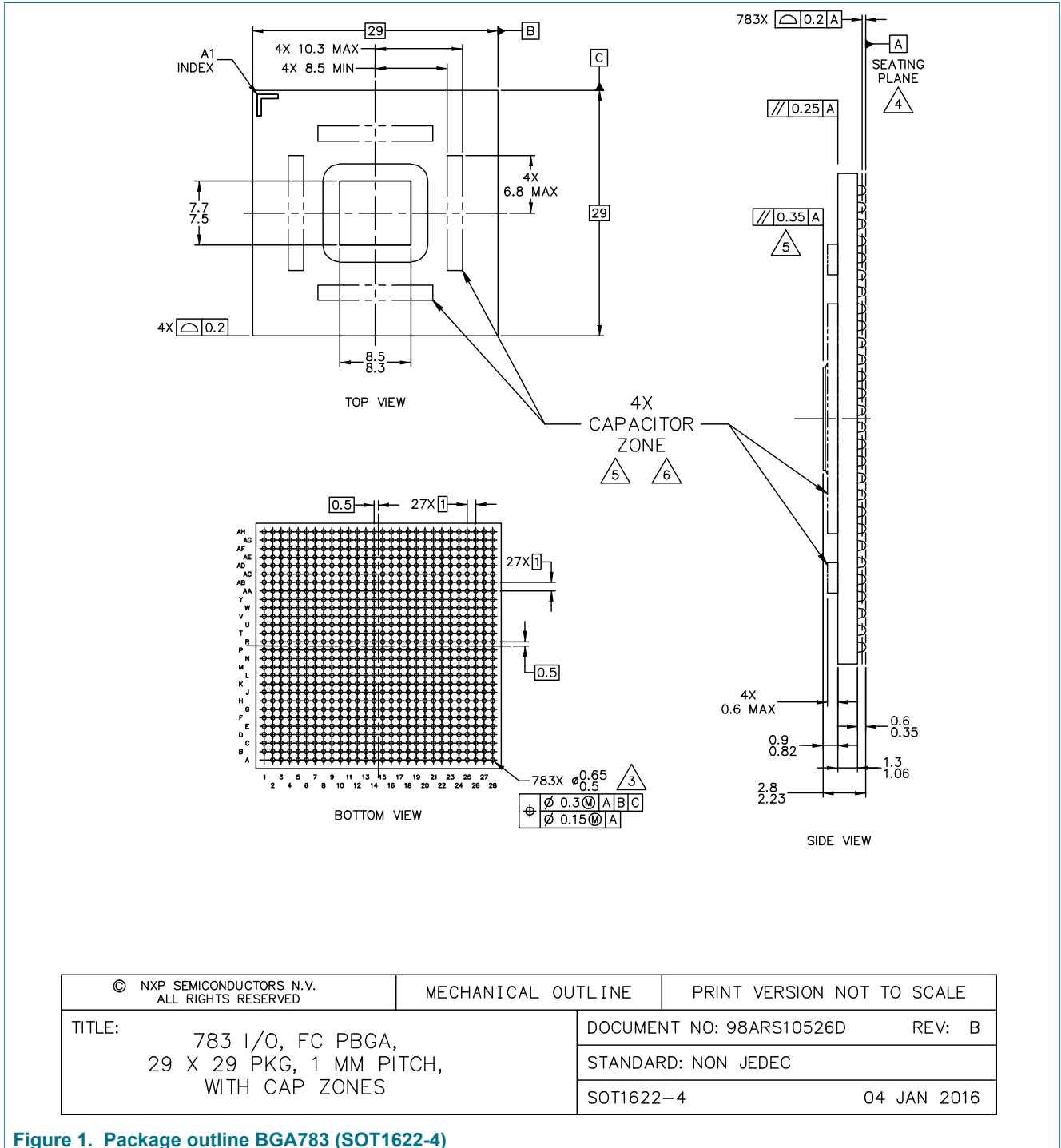


Figure 1. Package outline BGA783 (SOT1622-4)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. CAPACITORS MAY NOT BE PRESENT ON ALL PARTS. CARE MUST BE TAKEN MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS.
7. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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TITLE: 783 I/O, FC PBGA, 29 X 29 PKG, 1 MM PITCH, WITH CAP ZONES	DOCUMENT NO: 98ARS10526D		REV: B
	STANDARD: NON JEDEC		
	SOT1622-4		04 JAN 2016

Figure 2. Package outline note BGA783 (SOT1622-4)

3 Legal information

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